



SMD Comm X8G HT150C Flex, Ceramic, 3.9 pF, +/-0.25 pF, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1210
L	3.3mm +/-0.4mm
W	2.6mm +/-0.3mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm
R	U.6mm +/-U.25mm

Packaging Quantity

Т	0.78mm +/-0.20mm	Volt
S	1.5mm MIN	Diele
В	0.6mm +/-0.25mm	Tem
		Tem
Packaging Specifications		Cap
Packaging	T&R, 330mm, Plastic Tape	Cap Refe

10000

Specifications	
Capacitance	3.9 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.25 pF
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Stater	ments of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and
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